ASSOCIATION CONNECTS ELECTRONICS INDUSTRI	© Copyright 2005. IPC, B	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution											
Supplier Inform	mation												
Company name*			Company unique ID			Unique ID Authority				Response Date*			
nsemi										2024-05-21			
Contact Name		itle - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stew	vards	Produ	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
authorized Repres	sentative*	Title	Title - Representative			Phone - Representative*			Email	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Reques	quester Item Number Mfr Ite		per Mfr Item Name		E	Effective Date   Version   Manufa		Manufacturing	Site	Weight*	UOM	Unit Type	
	74LVX244		44MTCX 3V OCTAL BUFFER/LINE DRV		7 2	2024-05-21		PH4		73.596	mg	Each	
	g Proccess Information												
Termina	Terminal Plating / Grid Array Material		al Base Alloy	J-STD-020 MSL	Rating	Peak Process Body Temperature   Max Time at Pe		at Peak Temper	k Temperature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		(no CU Allo	CU Alloy 1			260	С	30 seco		seconds 3			
Comments													
vel 1 - maximum	time at peak temperature du	ring soldering	g is 10-30 seconds										
or more informat	tion regarding material comp	osition please	refer to page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.25	mg	Supplier	Silicon (Si)	7440-21-3		1.25	mg
Die Attach	0.136	mg	Supplier	Ethylene glycol dicyclopentenyl ether methacrylate	68586-19-6		0.0048	mg
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0009	mg
			Supplier	Silver (Ag)	7440-22-4		0.1304	mg
Lead Frame	30.624	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0459	mg
			Supplier	Silicon (Si)	7440-21-3		0.1991	mg
			В	Nickel (Ni)	7440-02-0		0.9187	mg
			Supplier	Copper (Cu)	7440-50-8		29.4603	mg
Mold Compound-Black	40.867	mg		Epoxy resin	proprietary data		3.8824	mg
			Supplier	Phenol Resin	Proprietary Data		2.0433	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2043	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.7369	mg
Plating	0.223	mg	Supplier	Palladium (Pd)	7440-05-3		0.006	mg
			В	Nickel (Ni)	7440-02-0		0.213	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg
Wire Bond - Au	0.496	mg	Supplier	Gold (Au)	7440-57-5		0.496	mg